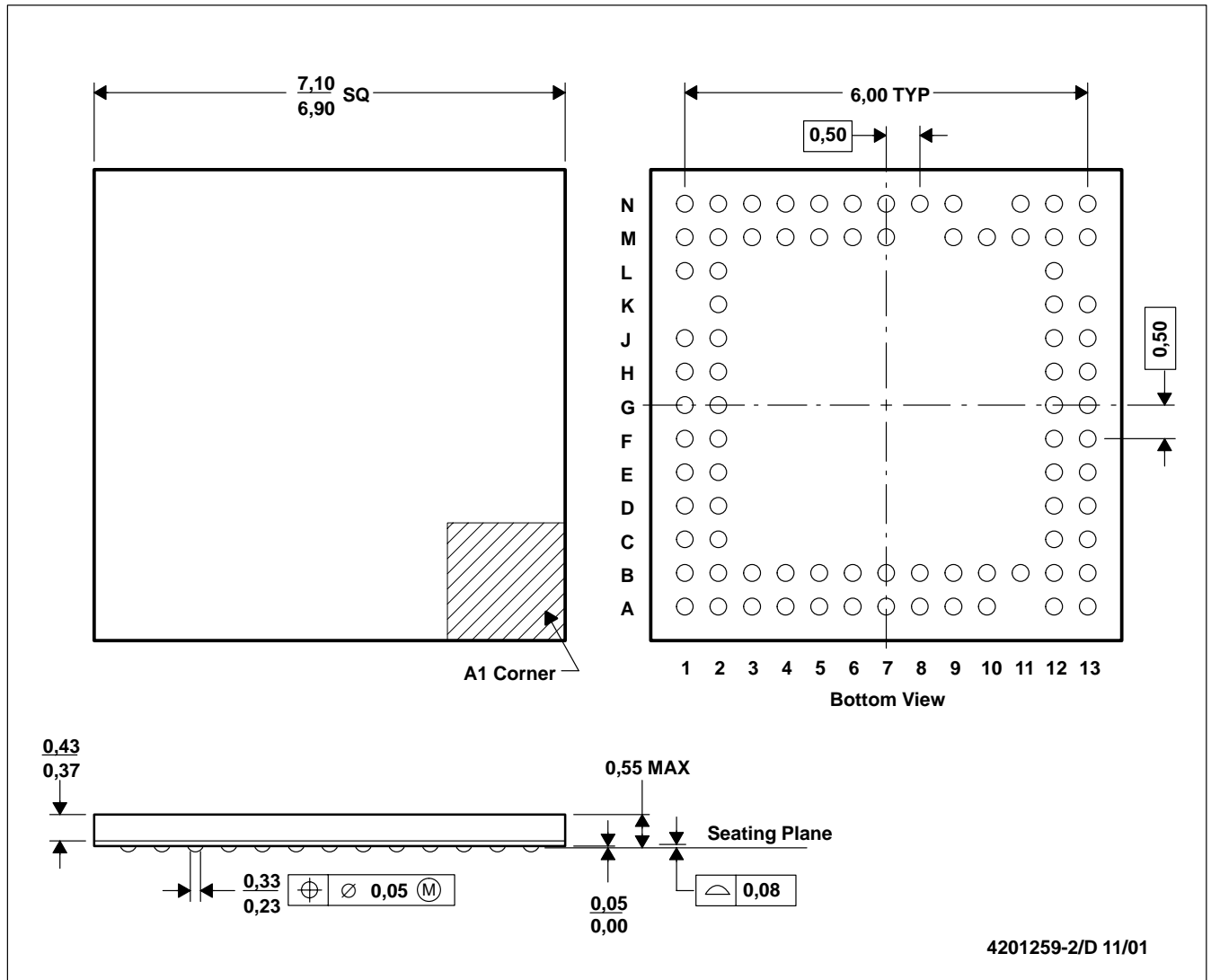


GSD (S-PLGA-N83)

PLASTIC LAND GRID ARRAY



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. MicroStar Junior™ configuration
 D. Falls within JEDEC MO-225

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